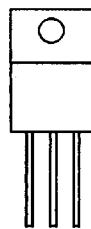


P-Channel Enhancement-Mode Transistor

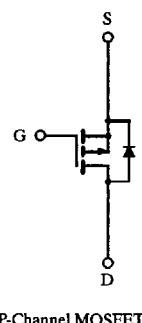
Product Summary

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-100	0.210	-17

TO-254AA
Hermetic Package

Case Isolated

Top View

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	-17	A
		-10.8	
Pulsed Drain Current	I_{DM}	-68	
Maximum Power Dissipation	P_D	100	W
		40	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$
Lead Temperature ($1/16"$ from case for 10 sec.)	T_L	300	

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	R_{thJA}		50	$^\circ\text{C/W}$
Maximum Junction-to-Case	R_{thJC}		1.25	
Case-to-Sink	R_{thCS}	0.2		

Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

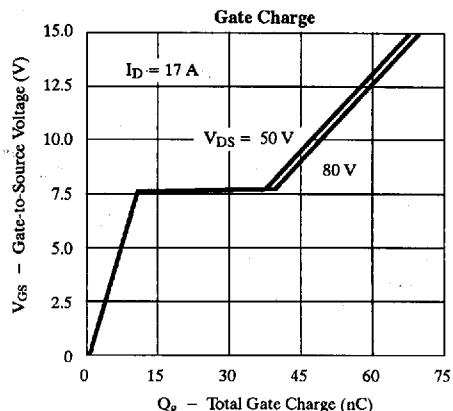
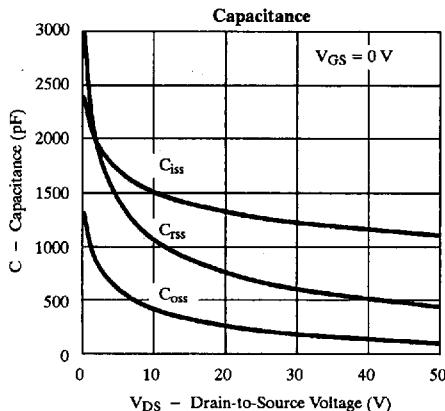
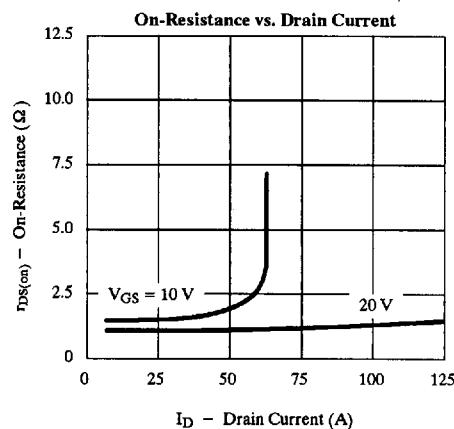
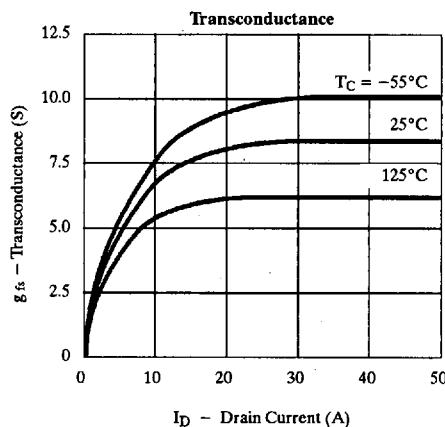
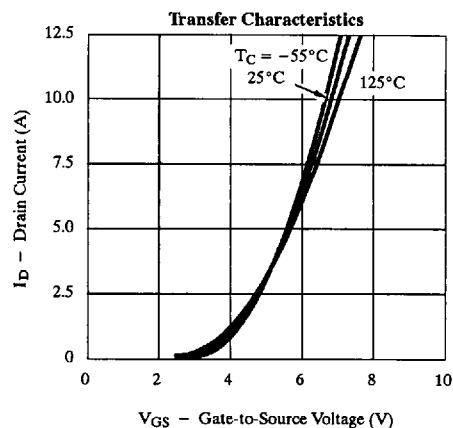
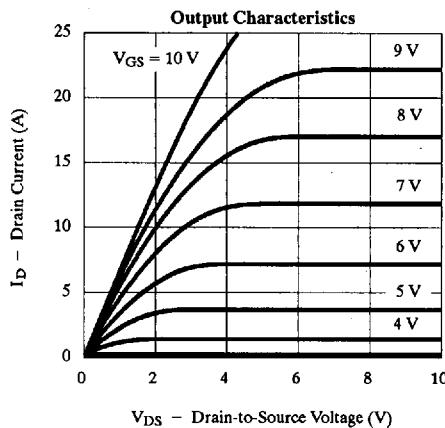
Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ ^a	Max	
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-100			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-2.0		-4.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -80 \text{ V}, V_{GS} = 0 \text{ V}$			-25	
		$V_{DS} = -80 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$			-250	μA
On-State Drain Current ^b	$I_{D(\text{on})}$	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}$	-17			A
Drain-Source On-State Resistance ^b	$r_{DS(\text{on})}$	$V_{GS} = -10 \text{ V}, I_D = -10.8 \text{ A}$		0.14	0.210	
		$V_{GS} = -10 \text{ V}, I_D = -10.8 \text{ A}, T_J = 125^\circ\text{C}$		0.22	0.32	Ω
Forward Transconductance ^b	g_f	$V_{DS} = -15 \text{ V}, I_D = -10.8 \text{ A}$	5.0	5.5		s
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		1300		pF
Output Capacitance	C_{oss}			750		
Reverse Transfer Capacitance	C_{rss}			300		
Total Gate Charge ^c	Q_g	$V_{DS} = -50 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -17 \text{ A}$		47	60	nC
Gate-Source Charge ^c	Q_{gs}			10	18	
Gate-Drain Charge ^c	Q_{gd}			27	36	
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = -50 \text{ V}, R_L = 2.7 \Omega$ $I_D = -17 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 4.7 \Omega$		10	30	ns
Rise Time ^c	t_r			50	80	
Turn-Off Delay Time ^c	$t_{d(off)}$			25	80	
Fall Time ^c	t_f			15	60	
Source-Drain Diode Ratings and Characteristics						
Continuous Current	I_S				-17	A
Pulsed Current	I_{SM}				-68	
Diode Forward Voltage ^b	V_{SD}	$I_F = -17 \text{ A}, V_{GS} = 0 \text{ V}$			-2.0	V
Reverse Recovery Time	t_{rr}	$I_F = -17 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		150		ns
Reverse Recovery Charge	Q_{rr}			0.3		μC

Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- c. Independent of operating temperature.

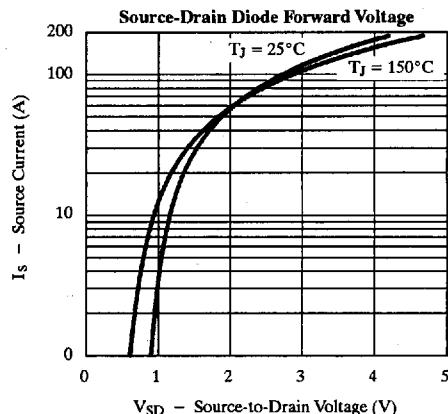
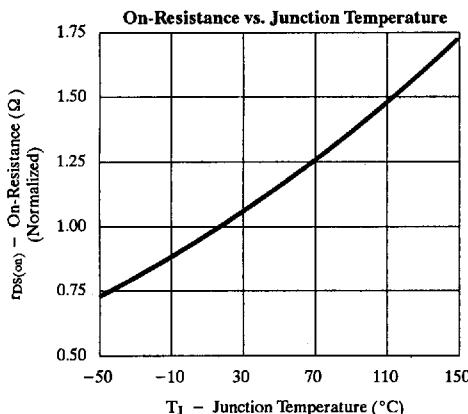
Typical Characteristics (25°C Unless Otherwise Noted)

Negative signs omitted for clarity.



2N7079**Typical Characteristics (25°C Unless Otherwise Noted)**

Negative signs omitted for clarity.

**Thermal Ratings**